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- 37 ((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated)) - 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) not (pumping adj plate)) and (wafer or substrate or (object adj2) DERWENT;	ĺ			US-PGPUB:	
- 37 ((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated)) - 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) not (pumping adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3))]			EPO; JPO:	
- 37 ((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated)) - 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) not (pumping adj plate)) not (pumping adj plate)) and (wafer or substrate or (object adj2) DERWENT;					
- 37 ((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated)) - 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 (US-PGPUB; pumping adj plate)) and (wafer or substrate or (object adj2 plate)) poc perwent; pumping adj plate)) and (wafer or substrate or (object adj2 plate)) poc perwent; pumping adj plate)]				
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91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 plate)) por (pumping adj plate)) and (wafer or substrate or (object adj2 plate))]	37			2003/10/06 13.09
- 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 plate)) por (pumping adj plate)) and (wafer or substrate or (object adj2 plate))			substrate or (object adjz treated))		
- 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 plate)) perwent; 18M_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB;					
- 91 ((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3) - 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 plate)) perwent; 2003/10/08 15:20				1	
or coat\$3 or deposit\$3) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; DERWENT;					
or coat\$3 or deposit\$3) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) US-PGPUB; US-PGPUB; US-PGPUB; EPO; JPO; DERWENT;	-	91			2003/10/08 15:20
61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) EPO; JPO; USPAT; US-PGPUB; EPO; JPO; DERWENT;					
- 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) DERWENT; US-PGPUB; EPO; JPO; DERWENT;			• • •		[
- 61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) BM_TDB				, ,	
61 (((pump\$3 adj plate) not (pumping adj plate)) and (etch\$3 USPAT; US-PGPUB; (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) 61 (((pump\$3 adj plate) not ((pump\$3 adj plate) not (US-PGPUB; EPO; JPO; DERWENT; DERWENT;					
or coat\$3 or deposit\$3)) not (((pump\$3 adj plate) not (pumping adj plate)) and (wafer or substrate or (object adj2 treated))) US-PGPUB; EPO; JPO; DERWENT;	_	64	(((numpt3 adj plate) not (numping adj plate)) and (at-t-t-2		2002/10/09 15:20
(pumping adj plate)) and (wafer or substrate or (object adj2 EPO; JPO; treated)))	-	61			Z003/10/08 15:29
treated)))					
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I IBM TDB I			treated)))		
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-	151	(((118/715,725) or (156/345.29)).CCLS.) and (exhaust	USPAT;	2003/10/08 16:21
		same (throttl\$3 or chok\$3))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	139	(((((118/715,725) or (156/345.29)).CCLS.) and (exhaust	USPAT;	2003/10/08 16:20
		same (throttl\$3 or chok\$3))) not (pumping adj plate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	22370	(pump\$3 adj plate) or (exhaust same (throttl\$3 or chok\$3))	USPAT;	2003/10/08 16:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	313	((pump\$3 adj plate) or (exhaust same (throttl\$3 or	USPAT;	2003/10/08 16:28
		chok\$3))) and skirt	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	